

H233-Z80-AAW1

High Density Server - 2U 2-Node DP 4 x PCIe GPUs



Features

- Supports up to 4 x Dual slot Gen5 GPUs
- 2U 2-node rear access server system
- Dual AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 4 x 1Gb/s LAN ports via Intel® I350-AM2
- 4 x 2.5" Gen4 NVMe hot-swap bays
- 4 x FHFL PCIe Gen5 x16 slots for GPUs
- 2 x LP PCIe Gen5 x16 slots
- 2 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Application

AI, AI Training, AI Inference, HPC, HCI, Hybrid/Private Cloud Server

Specification

Dimensions	2U 2-Node - Rear access (W440 x H87.5 x D877 mm)	Backplane Board	Speed and bandwidth: PCIe Gen4 x4
Motherboard	MZ83-HD0	TPM	1 x TPM headers with SPI interface (per node) - Optional TPM2.0 kit: CTM010
CPU	AMD EPYC™ 9005 Series Processors AMD EPYC™ 9004 Series Processors Dual processor per node cTDP up to 240W	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Socket	2 x LGA 6096 (Socket SP5)	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
Chipset	System on Chip	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Memory	12-Channel DDR5 RDIMM, 48 x DIMMs [EPYC 9005] RDIMM: Up to 6000 MT/s [EPYC 9004] RDIMM: Up to 4800 MT/s	System Fans	4 x 80x80x80mm (16,500rpm)
LAN	4 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Support NCSI function 2 x 10/100/1000 management LAN	Operating Properties	Operating temperature: 10°C to 30°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	Integrated in ASPEED® AST2600 x 2 - 2 x Mini-DP	Packaging Content	1 x H233-Z80-AAW1, 4 x CPU heatsinks, 1 x 3-Section Rail Kit, 1 x Mini-DP to D-Sub cable, 4 x GPU power cables (CPU 8pin) Packaging Dimensions: 1179 x 700 x 380 mm
Storage	Front hot-swap: 4 x 2.5" Gen4 NVMe	Part Numbers	Barebone package: 6NH233Z80DR000ACW1* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - RMA packaging: 6NH233Z80SR-RMA-A100
SAS	N/A		
RAID	N/A		
Expansion Slots	4 x FHFL PCIe Gen5 x16 slots for GPUs 2 x LP PCIe Gen5 x16 slots 2 x OCP NIC 3.0 PCIe Gen5 x16 slots		
Rear I/O	4 x USB 3.2 Gen1, 2 x Mini-DP, 4 x RJ45, 2 x MLAN		



Learn more at <https://www.GIGABYTE.com/enterprise>

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